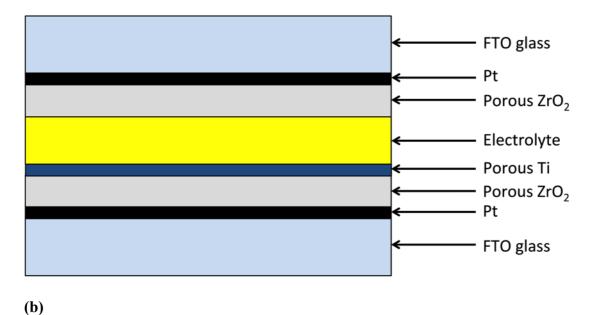
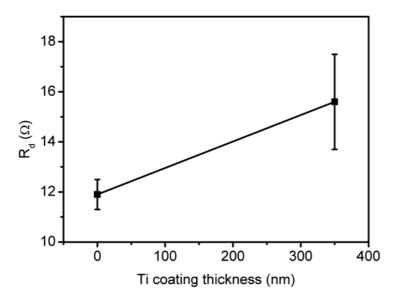
## Supplementary information

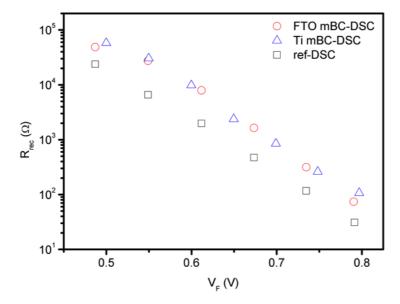
## **Supplementary information**

(a)





**Figure S1 (a)** Device setup for the EIS measurement of the triiodid/iodide diffusion resistance ( $R_d$ ) through the porous Ti and  $ZrO_2$  layers. The device has an active geometrical area of 0.16 cm<sup>2</sup>. The Pt catalytic layer was produced via thermal decomposition of  $H_2PtCl_6$ . The  $ZrO_2$  layer is identical to that used in mBC-DSCs.  $R_d$  were measured for devices without and with a sputter coated 350 nm Ti layer. EIS results obtained from data fitting are plotted in **(b)**.



**Figure S2** Recombination resistance  $R_{rec}$  for FTO mBC-DSCs, Ti mBC-DSCs and ref-DSCs retrieved by fitting EIS results to the classic transmission line model.  $V_F$  refers to 'Fermi level voltage', which is calculated by subtracting the Ohmic drop from the applied bias potential across the devices. <sup>18</sup> The plots of  $R_{rec}$  for all three types of devices show exponential dependency on the  $V_F$ , in accordance with the trend reported in literature. <sup>17, 20, 21</sup> Reduced recombination is shown for the mBC-DSCs compared to the ref-DSCs.